

# BASIC BLADE & BEAM HEADER

(0.50 mm) .0197" PITCH • BTH SERIES



## BTH

Mates:  
BSH

### SPECIFICATIONS

#### Insulator Material:

Black LCP

#### Contact Material:

Phosphor Bronze

#### Plating:

Au or Sn over  
50 μ" (1.27 μm) Ni

#### Current Rating:

2.0 A per pin  
(2 pins powered)

#### Operating Temp Range:

-55 °C to +125 °C

#### Voltage Rating:

175 VAC

#### Max Cycles:

100

### PROCESSING

#### Lead-Free Solderable:

Yes

#### SMT Lead Coplanarity:

Vertical=  
(0.10 mm) .004" max (030-090),  
(0.15 mm) .006" max (120-150)\*  
Right-angle=  
(0.15 mm) .006" max (030-090)\*  
\*(.004" stencil solution  
may be available; contact  
IPG@samtec.com)

#### Board Stacking:

For applications requiring more  
than two connectors per board  
or 90 positions or higher,  
contact ipg@samtec.com

### ALSO AVAILABLE

MOQ Required

30 μ" (0.76 μm) Gold  
Edge Mount Capability  
8 mm, 11 mm, 16 mm,  
19 mm and 22 mm Stack  
Height (Caution: Some  
automatic placement/  
inspection machines may  
have component height  
restrictions. Please consult  
machinery specifications.)  
(11 mm, 16 mm, 19 mm  
and 22 mm not available  
with 50 positions)



**Note:**  
Some lengths, styles and  
options are non-standard,  
non-returnable.

BTH	-	NO. OF POSITIONS PER ROW	-	01	-	PLATING OPTION	-	D	-	A	-	OTHER OPTION
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-030, -050, -060,  
-090, -120, -150

-F  
= Gold Flash  
on contact,  
Matte Tin on tail

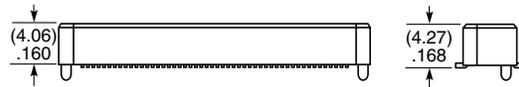
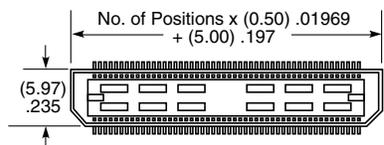
-L  
= 10 μ" (0.25 μm)  
Gold on contact,  
Matte Tin on tail

-C\*  
= Electro-Polished Selective  
50 μ" (1.27 μm) min  
Au over 150 μ" (3.81 μm)  
Ni on Signal Pins in contact  
area, Matte Tin over  
50 μ" (1.27 μm) min  
Ni on all solder tails  
(\*-C Plating passes  
10 year MFG testing)

-K  
= (7.00 mm) .276"  
DIA Polyimide  
Film Pick  
& Place Pad

-TR  
= Tape & Reel  
(120 positions  
maximum)

-FR  
= Full Reel  
Tape & Reel  
(must order  
maximum  
quantity per  
reel;  
contact  
Samtec for  
quantity breaks)  
(120 positions  
maximum)



### MATED HEIGHT

LEAD STYLE	MATED HEIGHT*
-01	(5.00 mm) .1971"

\*Processing conditions  
will affect mated height.

BTH	-	NO. OF POSITIONS PER ROW	-	01	-	PLATING OPTION	-	D	-	RA	-	WT	-	OTHER OPTION
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-030, -060, -090

-F  
= Gold Flash on  
contact, Matte  
Tin on tail

-L  
= 10 μ" (0.25 μm)  
Gold on contact,  
Matte Tin on tail

-K  
= (7.00 mm)  
.276" DIA  
Polyimide  
Film Pick &  
Place Pad

